

September 2000 Revised August 2001

## 74LCX162244

# Low Voltage 16-Bit Buffer/Line Driver with 26 $\Omega$ Series Resistors in Outputs

## **General Description**

The LCX162244 contains sixteen non-inverting buffers with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble controlled. Each nibble has separate 3-STATE control inputs which can be shorted together for full 16-bit operation.

The LCX162244 is designed for low voltage (2.5V or 3.3V)  $V_{CC}$  applications with capability of interfacing to a 5V signal environment.

In addition, the outputs include equivalent 26 $\Omega$  (nominal) series resistors to reduce overshoot and undershoot and are designed to sink/source up to 12 mA at  $V_{CC}=3.0V$ .

The LCX162244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

## **Features**

- 5V tolerant inputs and outputs
- 2.3V-3.6V V<sub>CC</sub> specifications provided
- $\blacksquare$  Outputs include equivalent series resistance of  $26\Omega$  to make external termination resistors unnecessary and reduce overshoot and undershoot
- 5.3 ns  $t_{PD}$  max ( $V_{CC} = 3.0V$ ), 20  $\mu$ A  $I_{CC}$  max
- Power down high impedance inputs and outputs
- $\blacksquare$  ±12 mA output drive (V<sub>CC</sub> = 3.0V)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

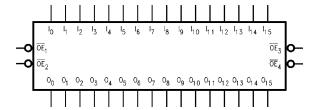
# **Ordering Code:**

Order Number	Package Number	Package Description
74LCX162244GX (Note 1)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [TAPE and REEL]
74LCX162244MEA (Note 2)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LCX162244MTD (Note 2)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 1: BGA package available in Tape and Reel only.

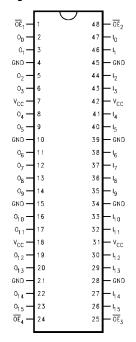
Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### **Logic Symbol**

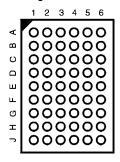


# **Connection Diagrams**

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

# **Pin Descriptions**

Pin Names	Description
<del>OE</del> <sub>n</sub>	Output Enable Input (Active LOW)
I <sub>0</sub> -I <sub>15</sub>	Inputs
I <sub>0</sub> –I <sub>15</sub> O <sub>0</sub> –O <sub>15</sub>	Outputs
NC	No Connect

# **FBGA Pin Assignments**

	1	2	3	4	5	6
Α	O <sub>0</sub>	NC	OE <sub>1</sub>	OE <sub>2</sub>	NC	I <sub>0</sub>
В	O <sub>2</sub>	O <sub>1</sub>	NC	NC	I <sub>1</sub>	l <sub>2</sub>
С	O <sub>4</sub>	O <sub>3</sub>	V <sub>CC</sub>	V <sub>CC</sub>	l <sub>3</sub>	I <sub>4</sub>
D	O <sub>6</sub>	O <sub>5</sub>	GND	GND	I <sub>5</sub>	I <sub>6</sub>
E	O <sub>8</sub>	O <sub>7</sub>	GND	GND	I <sub>7</sub>	I <sub>8</sub>
F	O <sub>10</sub>	O <sub>9</sub>	GND	GND	I <sub>9</sub>	I <sub>10</sub>
G	O <sub>12</sub>	O <sub>11</sub>	V <sub>CC</sub>	V <sub>CC</sub>	I <sub>11</sub>	I <sub>12</sub>
Н	O <sub>14</sub>	O <sub>13</sub>	NC	NC	I <sub>13</sub>	I <sub>14</sub>
J	O <sub>15</sub>	NC	OE <sub>4</sub>	$\overline{OE}_3$	NC	I <sub>15</sub>

## **Truth Tables**

Inp	Outputs	
OE <sub>1</sub>	I <sub>0</sub> –I <sub>3</sub>	O <sub>0</sub> -O <sub>3</sub>
L	L	L
L	Н	Н
н	×	Z

Inp	Outputs	
OE <sub>2</sub>	I <sub>4</sub> –I <sub>7</sub>	O <sub>4</sub> -O <sub>7</sub>
L	L	L
L	Н	Н
Н	X	Z

Inp	Outputs	
OE₃	I <sub>8</sub> –I <sub>11</sub>	O <sub>8</sub> -O <sub>11</sub>
L	L	L
L	Н	Н
Н	X	Z

Inp	Inputs		
ŌE₄	O <sub>12</sub> -O <sub>15</sub>		
L	L	L	
L	Н	Н	
Н	X	Z	

H = HIGH Voltage Level L = LOW Voltage Level

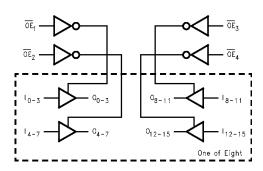
X = Immaterial Z = High Impedance

# **Functional Description**

The LCX162244 contains sixteen non-inverting buffers with 3-STATE standard outputs. The device is designed with  $26\Omega$  series resistors in the outputs. This design reduces line noise in applications such as memory address drivers, clock drivers and bus transceiver/transmitters. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of the other. The control pins

can be shorted together to obtain full 16-bit operation. The 3-STATE outputs are controlled by an Output Enable  $(\overline{OE}_n)$  input for each nibble. When  $\overline{OE}_n$  is LOW, the outputs are in 2-state mode. When  $\overline{OE}_n$  is HIGH, the outputs are in the high impedance mode, but this does not interfere with entering new data into the inputs.

# **Logic Diagram**



# Absolute Maximum Ratings(Note 3)

Symbol	Parameter	Value	Conditions	Units
V <sub>CC</sub>	Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	-0.5 to +7.0		V
Vo	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		$-0.5$ to $V_{CC} + 0.5$	Output in HIGH or LOW State (Note 4)	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	$V_O > V_{CC}$	ША
Io	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature	-65 to +150		°C

# **Recommended Operating Conditions** (Note 5)

Symbol	Parameter			Max	Units
V <sub>CC</sub>	Supply Voltage Operation		2.0	3.6	V
		Data Retention	1.5	3.6	v
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0	V <sub>CC</sub>	V
		3-STATE	0	5.5	v
I <sub>OH</sub> /I <sub>OL</sub>	Output Current	$V_{CC} = 3.0V - 3.6V$		±12	
		$V_{CC} = 2.7V - 3.0V$ $V_{CC} = 2.3V - 2.7V$		±8	mA
		$V_{CC} = 2.3V - 2.7V$		±4	
T <sub>A</sub>	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V–2.0V, V <sub>CC</sub> = 3.0V		0	10	ns/V

Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 4:  $I_O$  Absolute Maximum Rating must be observed.

Note 5: Unused control inputs must be held HIGH or LOW. They may not float.

## **DC Electrical Characteristics**

Symbol	Parameter	Conditions	V <sub>CC</sub>	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units	
Зушьог	Farameter	Conditions	(V)	Min	Max	Units	
V <sub>IH</sub>	HIGH Level Input Voltage		2.3 – 2.7	1.7		V	
			2.7 – 3.6	2.0		V	
V <sub>IL</sub>	LOW Level Input Voltage		2.3 – 2.7		0.7	V	
			2.7 – 3.6		0.8	V	
V <sub>ОН</sub>	HIGH Level Output Voltage	$I_{OH} = -100  \mu A$	2.3 – 3.6	V <sub>CC</sub> - 0.2			
		$I_{OH} = -4 \text{ mA}$	2.3	1.8			
		$I_{OH} = -4 \text{ mA}$	2.7	2.2		V	
		I <sub>OH</sub> = -6 mA	3.0	2.4		V	
		I <sub>OH</sub> = -8 mA	2.7	2.0			
		$I_{OH} = -12 \text{ mA}$	3.0	2.0			
/ <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100 μA	2.3 – 3.6		0.2		
		I <sub>OL</sub> = 4 mA	2.3		0.6		
		I <sub>OL</sub> = 4 mA	2.7		0.4	V	
		I <sub>OL</sub> = 6 mA	3.0		0.55	v	
		I <sub>OL</sub> = 8 mA	2.7		0.6		
		I <sub>OL</sub> = 12 mA	3.0		0.8		
ı	Input Leakage Current	$0 \le V_1 \le 5.5$	2.3 – 3.6		±5.0	μΑ	
OZ	3-STATE Output Leakage	0 ≤ V <sub>O</sub> ≤ 5.5V	2.3 - 3.6		±5.0	μА	
		$V_I = V_{IH}$ or $V_{IL}$			-		

# DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = -40°0	C to +85°C	Units
	i arameter	Conditions	(V)	Min	Max	Offics
I <sub>OFF</sub>	Power-Off Leakage Current	$V_{IN}$ or $V_{O} = 5.5V$	0		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.3 – 3.6		20	μΑ
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$V_{IH} = V_{CC} - 0.6V$	2.3 – 3.6		500	μΑ

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

## **AC Electrical Characteristics**

		$T_A = -40$ °C to $+85$ °C, $R_L = 500 \Omega$						
Symbol		V <sub>CC</sub> = 3.3	3V ± 0.3V	V <sub>CC</sub>	= 2.7V	V <sub>CC</sub> = 2.	5V ± 0.2V	Unita
	Parameter	C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 30 pF		Units
		Min	Max	Min	Max	Min	Max	
t <sub>PHL</sub>	Propagation Delay	1.0	5.3	1.0	6.0	1.0	6.4	
t <sub>PLH</sub>	Data to Output	1.0	5.3	1.0	6.0	1.0	6.4	ns
t <sub>PZL</sub>	Output Enable Time	1.0	6.3	1.0	7.1	1.0	8.2	
t <sub>PZH</sub>		1.0	6.3	1.0	7.1	1.0	8.2	ns
t <sub>PLZ</sub>	Output Disable Time	1.0	5.4	1.0	5.7	1.0	6.5	20
t <sub>PHZ</sub>		1.0	5.4	1.0	5.7	1.0	6.5	ns
t <sub>OSHL</sub>	Output to Output Skew (Note 8)		1.0					20
t <sub>OSLH</sub>			1.0					ns

Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design.

# **Dynamic Switching Characteristics**

Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = 25°C	Units
			(V)	Typical	
V <sub>OLP</sub>	Quiet Output Dynamic Peak V <sub>OL</sub>	$C_L = 50 \text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$	3.3	0.35	V
		$C_L = 50 \text{ pF, V}_{IH} = 3.3\text{V, V}_{IL} = 0\text{V}$ $C_L = 30 \text{ pF, V}_{IH} = 2.5\text{V, V}_{IL} = 0\text{V}$	2.5	0.25	V
V <sub>OLV</sub>	Quiet Output Dynamic Valley V <sub>OL</sub>	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.35	V
		$C_L = 30 \text{ pF, } V_{IH} = 2.5 \text{V, } V_{IL} = 0 \text{V}$	2.5	-0.25	V

# Capacitance

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = Open, V_I = 0V \text{ or } V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3V$ , $V_I = 0V$ or $V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{CC} = 3.3V, V_{I} = 0V \text{ or } V_{CC}, f = 10 \text{ MHz}$	20	pF

## AC LOADING and WAVEFORMS Generic for LCX Family

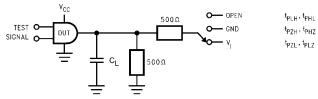
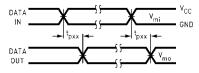
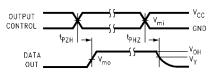


FIGURE 1. AC Test Circuit ( $C_L$  includes probe and jig capacitance)

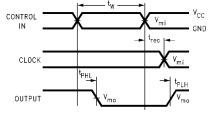
$V_{l}$	CL
6V for $V_{CC} = 3.3V, 2.7V$	50 pF
$V_{CC}$ * 2 for $V_{CC}$ = 2.5V	30 pF



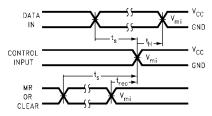
**Waveform for Inverting and Non-Inverting Functions** 



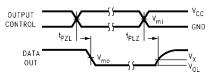
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and  $\mathbf{t}_{\text{rec}}$  Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

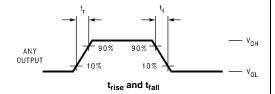
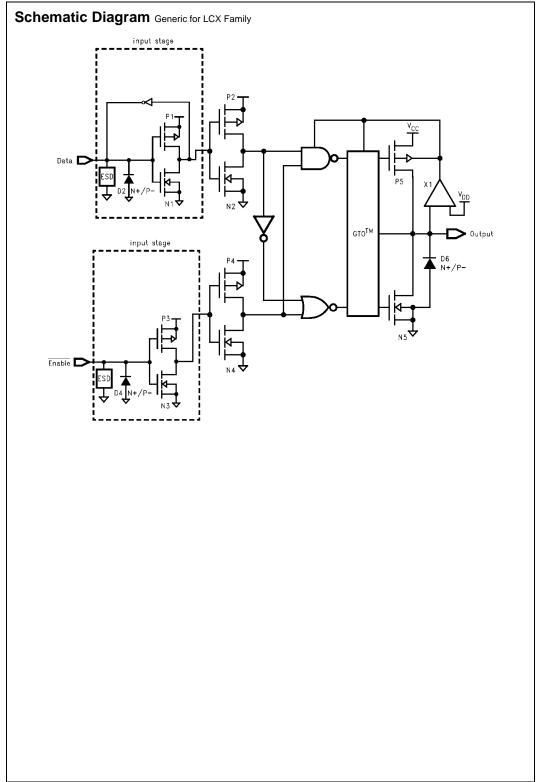
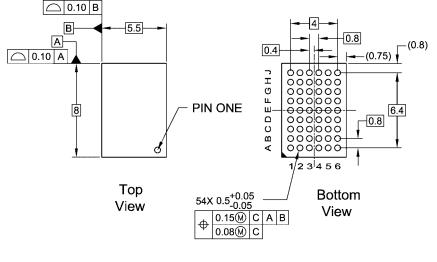


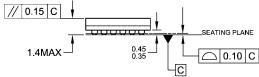
FIGURE 2. Waveforms (Input Characteristics; f = 1MHz,  $t_r = t_f = 3ns$ )

Symbol	V <sub>CC</sub>			
Symbol	$\textbf{3.3V} \pm \textbf{0.3V}$	2.7V	$\textbf{2.5V} \pm \textbf{0.2V}$	
V <sub>mi</sub>	1.5V	1.5V	V <sub>CC</sub> /2	
V <sub>mo</sub>	1.5V	1.5V	V <sub>CC</sub> /2	
V <sub>x</sub>	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.15V	
V <sub>y</sub>	V <sub>OH</sub> – 0.3V	V <sub>OH</sub> – 0.3V	V <sub>OH</sub> – 0.15V	



# Physical Dimensions inches (millimeters) unless otherwise noted



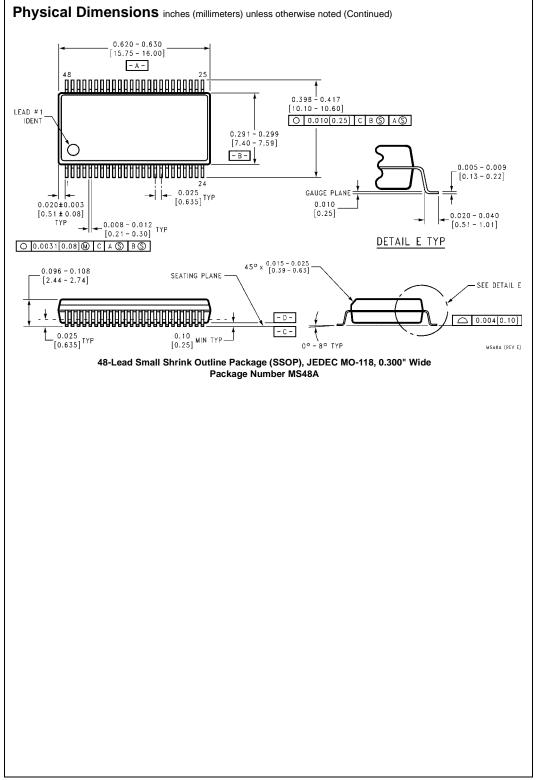


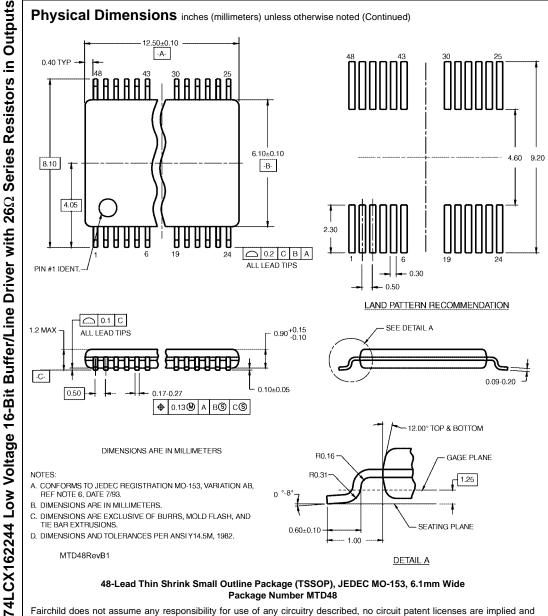
#### NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
  .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
  D. DRAWING CONFORMS TO ASME Y14.5M-1994

#### BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A Preliminary





48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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